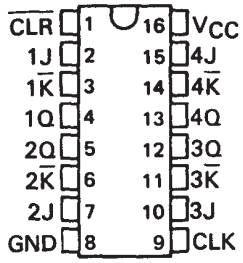
- Four J-$\overline{K}$ Flip-Flops in a Single Package . . . Can Reduce FF Package Count by 50%
- Common Positive-Edge-Triggered Clocks with Hysteresis . . . Typically 200 mV
- Fully Buffered Outputs
- Typical Clock Input Frequency . . . 45 MHz

SN54376 . . . J PACKAGE
SN74376 . . . N PACKAGE
(TOP VIEW)



description

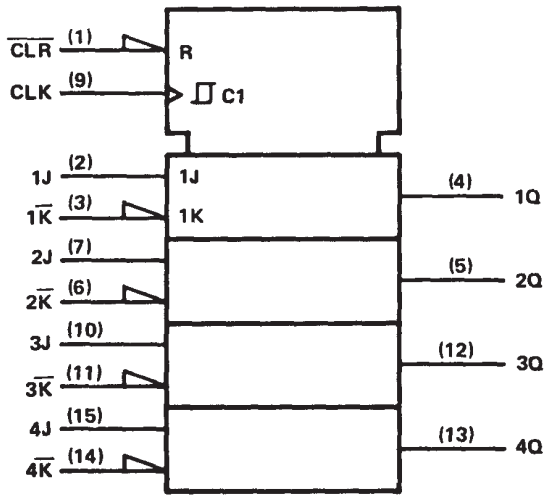
These quadruple TTL J-$\overline{K}$ flip-flops incorporate a number of third-generation IC features that can simplify system design and reduce flip-flop package count by as much as 50%. They feature hysteresis at the clock input, fully buffered outputs, and direct clear capability. The positive-edge-triggered SN54376 and SN74376 are directly compatible with most Series 54/74 MSI registers.

The SN54376 is characterized for operation over the full military temperature range of −55°C to 125°C; the SN74376 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (EACH FLIP-FLOP)

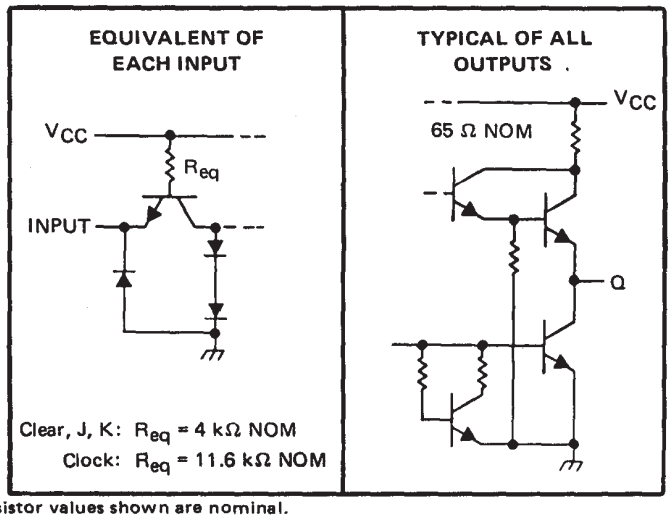
COMMON INPUTS		INPUTS		OUTPUT
CLEAR	CLOCK	J	$\overline{K}$	Q
L	X	X	X	L
H	↑	L	H	Q_0
H	↑	H	H	H
H	↑	L	L	L
H	↑	H	L	TOGGLE
H	L	X	X	Q_0

logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



Resistor values shown are nominal.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54376 . . . . . −55°C to 125°C
SN74376 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.

recommended operating conditions

		SN54376			SN74376			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−800			−800	μA
Low-level output current, I_{OL}				16			16	mA
Clock frequency		0		30	0		30	MHz
Pulse width, t_w	Clock high	22			22			ns
	Clock low	12			12			
	Preset or clear low	12			12			
Setup time, t_{su}	J, $\overline{K}$ inputs	0↑			0↑			ns
	Clear inactive state	10↑			10↑			
Input hold time, t_h		20↑			20↑			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↑↓The arrow indicates the edge of the clock pulse used for reference: ↑ for the rising edge, ↓ for the falling edge.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage			2			V
V_{IL}	Low-level input voltage					0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −12 mA			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OH} = −800 μA	2.4	3.4		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OL} = 16 mA		0.2	0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V			1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.4 V			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−30		−85	mA
I_{CC}	Supply current	V_{CC} = MAX			52	74	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	C_L = 15 pF, R_L = 400 Ω, See Note 2	30	45		MHz
t_{PHL}	Propagation delay time, high-to-low-level output from clear			17	30	ns
t_{PLH}	Propagation delay time, low-to-high-level output from clock			22	35	ns
t_{PHL}	Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN54376J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74376N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74376N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54376J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54376J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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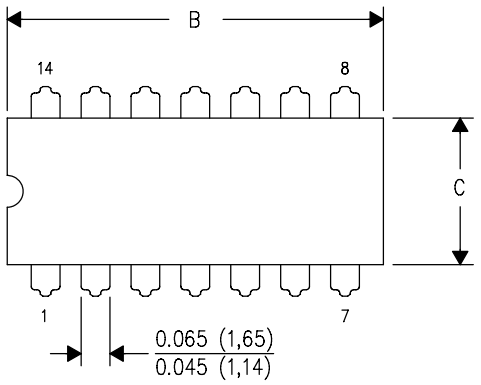
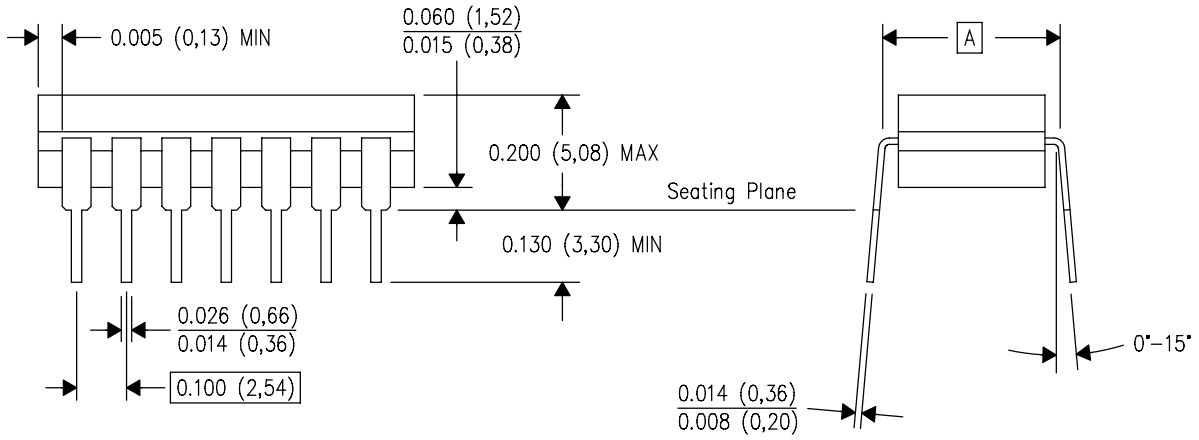
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



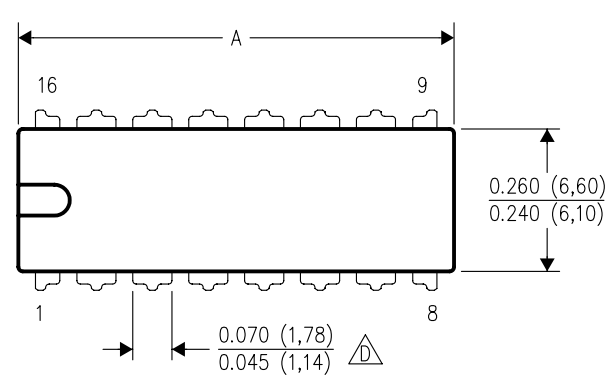
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

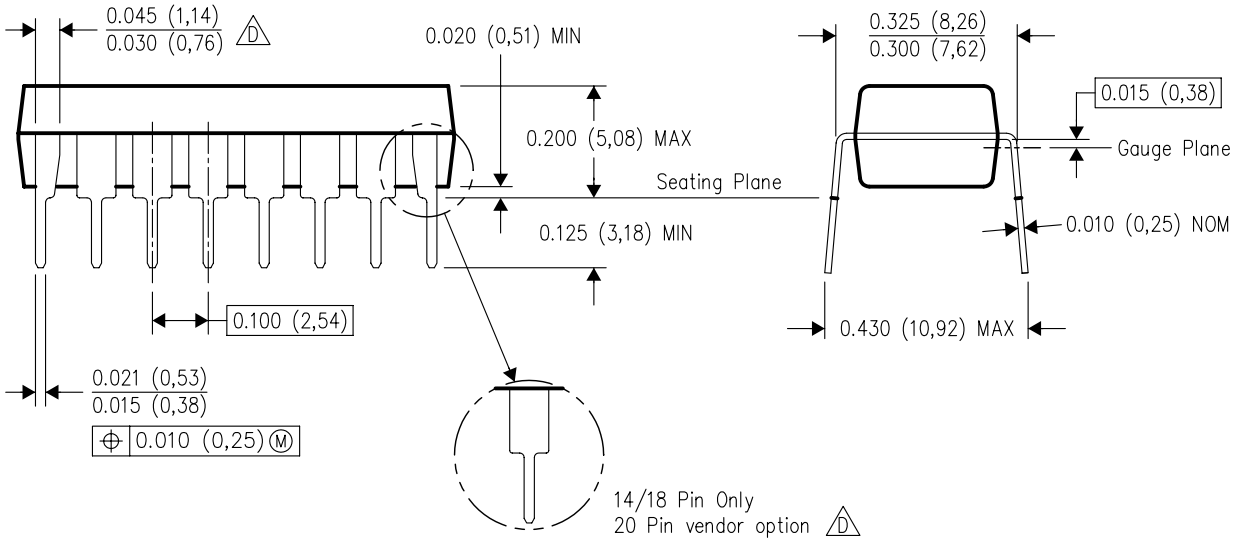
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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